APPLICA	BLE S	TANDAR	RD								
	Operati Temper	ng ature Range	-55 °C to 85 °	C (1)		rage nperatur	e Range		-10 °C to 6	0 °C	(2)
Rating	Voltage		50 V AC	50 V AC			orage Humidity Range		Relative humidity 85	% max	
	Curren	t	0.5 A			perating Humidity Range			(Not dewed)		
			SPEC	IFICA	TION	S					
IT	EM		TEST METHOD			REQUIREMENTS				QT	АТ
CONSTRI	JCTIO	N									
General Exa	mination	Visu	Visually and by measuring instrument.				ing to dra	wing.		×	×
Marking			Confirmed visually.							×	×
			TERISTICS								
Contact Resi			100 mA(DC or 1000Hz)			70 mΩ MAX .				×	_
Insulation Re			100 V DC.			100 MΩ MIN.				×	_
Voltage Prod			150 V AC for 1 min. ACTERISTICS			No flashover or breakdown.				×	×
Insertion And						Incortic	n Force:		14 N MAX.	Ι ν	1
Withdrawal F		liviea	Measured by applicable connector.			Withdrawal Force: 1.8 N MIN.				×	
Mechanical Operation		n 50 ti	50 times insertions and extractions.			_	Contact Resistance:				_
						Variation from initial value 20 m Ω or less.					
						② No damage, crack and looseness of parts.					
Vibration		Sing	Frequency 10 to 55 to 10Hz, approx 5min Single Amplitude: 0.75 mm, 10 cycles for 3 axial directions.			① No electrical discontinuity of 1 μs. ② No damage, crack and looseness of parts.				×	-
Shock		490	490 m/s ² , duration of pulse 11 ms								_
		at 3	at 3 times for 3 both axial directions.								
ENVIRON	MENT		RACTERISTICS								
Damp Heat (Steady state	·)	Expo	Exposed at 40±2 °C, 90 ~ 95 %, 96 h.			① Contact Resistance: Variation from initial value 20 mΩ or less.				×	_
Rapid Chang Temperature		Time Unde	Temperature -55 → +85 °C Time 30 → 30 min. Under 5 cycles. (Relocation time to chamber:within 2~3 MIN)			 Insulation Resistance : 100 MΩ MIN. No damage, crack and looseness of parts. 				×	_
Cold			Exposed at -55°C, 96 h			 ① Contact Resistance: Variation from initial value 20 mΩ or less. ② No damage, crack and looseness of parts. 				×	-
Dry Heat		Expo	Exposed at 85°C, 96 h							×	-
Sulfur Dioxid	e		ed at 25±2°C, 75±5%RH, 25 PPM for 96 h. standard : JIS C 60068)			 No defect such as corrosion which impairs the function of connector. Contact Resistance: variation from initial value 20 mΩ or less. 				×	_
Resistance to Soldering He		Pe Re	eflow Soldering : eak TMP : 260°CMAX eflow TMP: 220°CMIN for 60sec oldering Irons : 360°C MAX, for 5	TMP : 260°CMAX			No deformation of case of excessive looseness of the terminal.				_
Solderability		Sold	d at solder temperature C for immersion duration, 3 sec.			A new uniform coating of solder shall cover a minimum of 95 % of the surface being immersed.				×	_
COUN	IT _	DESCF	RIPTION OF REVISIONS		DESIG	NED			CHECKED	DA	TE
⚠											
REMARKS			ture rise caused by current-carrying. eans a long-term storage state for the unpacked part to PCB.			APPROVED		-	HS. OKAWA	14. 05. 29	
		ssembly to PC					CHECK	_	KN. SHIBUYA		5. 29
						DESIGNED		-	TS. 00N0	14. 05. 29	
Unless oth	erwise	specified,	refer to JIS-C-5402.				DRAWN		TS. 00N0	14. 05. 29	
Note QT:Q	ualificati		:Assurance Test X:Applicable Tes			RAWING NO.			ELC4-350411-00		
HS.			CIFICATION SHEET		PART	NO.			FX20-20S-0. 5SH	<u> </u>	
11.7		HIROSI	E ELECTRIC CO., LTD.	o., LTD. CODE		NO.	CL	CL570-1611-1-00			1/1